

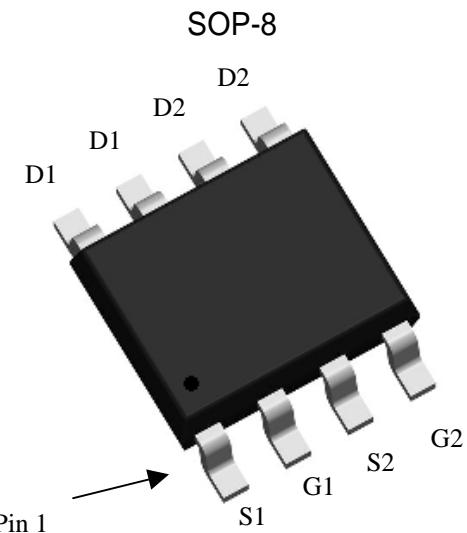
Dual P-Channel Logic Level Enhancement Mode Power MOSFET

Features:

- $R_{DS(ON)}=24m\Omega$ (max.)@ $V_{GS}=-10V$, $I_D=-8A$
- Simple drive requirement
- Low on-resistance
- Fast switching speed
- Dual P-ch MOSFET package
- Pb-free lead plating & Halogen-free package

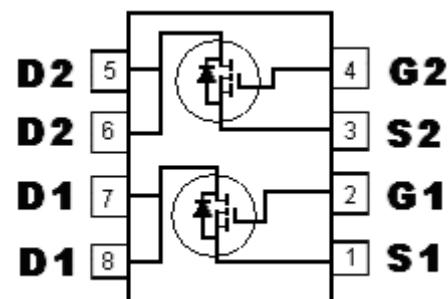
BV_{DSS}	-30V
I_D @ $V_{GS}=-10V$, $T_c=25^{\circ}\text{C}$	-8A
$R_{DS(on)(MAX)}$ @ $V_{GS}=-10V$, $I_D=-8A$	18m Ω (typ.)
$R_{DS(on)(MAX)}$ @ $V_{GS}=-4.5V$, $I_D=-6A$	27m Ω (typ.)

Outline



Equivalent Circuit

KWB24B03Q8



G : Gate D : Drain S : Source

Ordering Information

Device	Package	Shipping
KWB24B03Q8	SOP-8 (Pb-free lead plating and halogen-free package)	2500 pcs / tape & reel

Absolute Maximum Ratings ($T_a=25^\circ C$)

Parameter	Symbol	Limits	Unit
Drain-Source Voltage	V_{DS}	-30	V
Gate-Source Voltage	V_{GS}	± 25	
Continuous Drain Current, $V_{GS}=-10V$, $T_c=25^\circ C$	I_D	-8	A
Continuous Drain Current, $V_{GS}=-10V$, $T_c=100^\circ C$		-6	
Pulsed Drain Current (Note 1)		-32	
Avalanche Current	I_{AS}	-12	
Avalanche Energy @ $L=1mH$, $I_D=-8A$, $R_G=25\Omega$	E_{AS}	32	mJ
Repetitive Avalanche Energy @ $L=0.05mH$ *2	E_{AR}	8	
Power Dissipation	$T_A=25^\circ C$ (Note 3)	2.4	W
		1.3	
Operating Junction and Storage Temperature Range	T_j ; T_{stg}	-55~+175	°C

100% UIS testing in condition of $V_D=-15V$, $L=0.1mH$, $V_G=-10V$, $I_L=-8A$, Rated $V_{DS}=-30V$ P-CH

Thermal Data

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-case, max	$R_{th,j-c}$	25	°C/W
Thermal Resistance, Junction-to-ambient, max	$R_{th,j-a}$	62.5 *3	

Note : 1. Pulse width limited by maximum junction temperature
 2. Duty cycle $\leq 1\%$
 3. Surface mounted on 1 in²copper pad of FR-4 board, 125°C/W when mounted on minimum copper pad

Characteristics ($T_j=25^\circ C$, unless otherwise specified)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Static					
BV_{DSS}	-30	-	-	V	$V_{GS}=0V$, $I_D=-250\mu A$
$V_{GS(th)}$	-1	-1.5	-2.5		$V_{DS} = V_{GS}$, $I_D=-250\mu A$
I_{GSS}	-	-	± 100	nA	$V_{GS}=\pm 25V$
ID_{SS}	-	-	-1	μA	$V_{DS}=-24V$, $V_{GS}=0V$
	-	-	-10		$V_{DS}=-20V$, $V_{GS}=0V$, $T_j=125^\circ C$
$I_{D(ON)}$ *1	-8	-	-	A	$V_{DS}=-5V$, $V_{GS}=-10V$
* $R_{D(S)(ON)}$ *1	-	18	24	$m\Omega$	$V_{GS}=-10V$, $I_D=-8A$
	-	27	30		$V_{GS}=-4.5V$, $I_D=-6A$
G_{FS} *1	-	13	-	S	$V_{DS}=-5V$, $I_D=-8A$
Dynamic					
$Q_g(V_{GS}=-10V)$ *1, 2	-	24	-	nC	$I_D=-8A$, $V_{DS}=-15V$, $V_{GS}=-10V$
$Q_g(V_{GS}=-5V)$ *1, 2	-	16.1	-		
Q_{gs} *1, 2	-	6.8	-		
Q_{gd} *1, 2	-	8	-		

td(ON) *1, 2	-	9.3	-	ns	VDS=-15V, ID=-1A, VGS=-10V, RG=2.7Ω
tr *1, 2	-	6.1	-		
td(OFF) *1, 2	-	27	-		
tf *1, 2	-	8	-		
Ciss	-	2006	-	pF	VGS=0V, VDS=-15V, f=1MHz
Coss	-	200	-		
Crss	-	153	-		
Rg	-	4	-		VGS=15mV, VDS=0V, f=1MHz

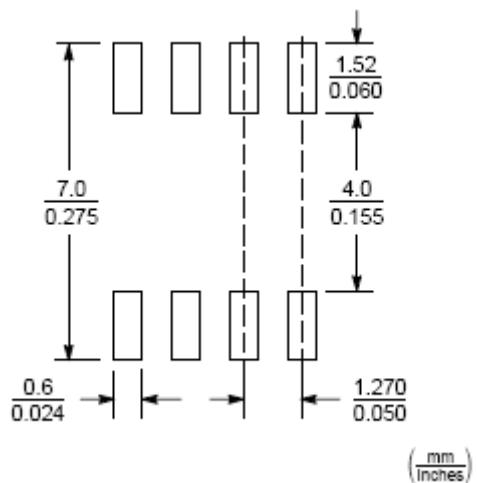
Source-Drain Diode

IS *1	-	-	-2.3	A	
ISM *3	-	-	-9.2		
VSD *1	-	-	-1.2	V	IF= Is, VGS=0V
ttr *1	-	32	-	ns	IF= Is, dIf/dt=100A/μs
Qrr *1	-	26	-		

Note : *1.Pulse Test : Pulse Width≤300μs, Duty Cycle≤2%

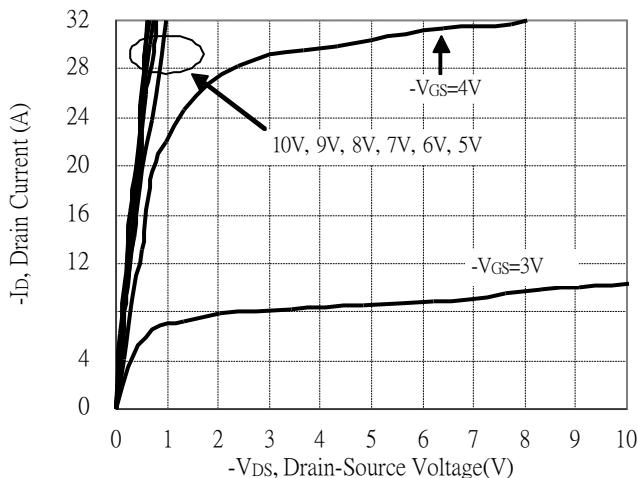
*2.Independent of operating temperature

*3.Pulse width limited by maximum junction temperature.

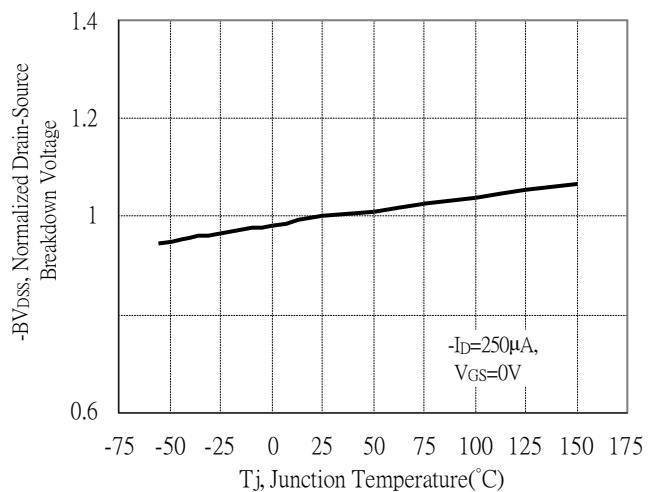
Recommended Soldering Footprint


Typical Characteristics

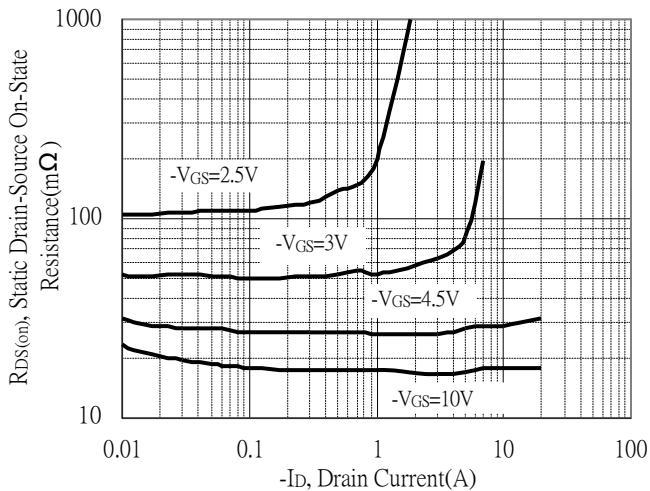
Typical Output Characteristics



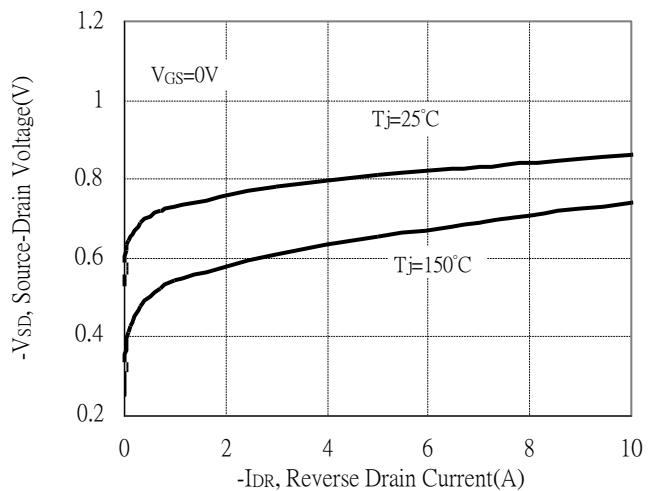
Breakdown Voltage vs Ambient Temperature



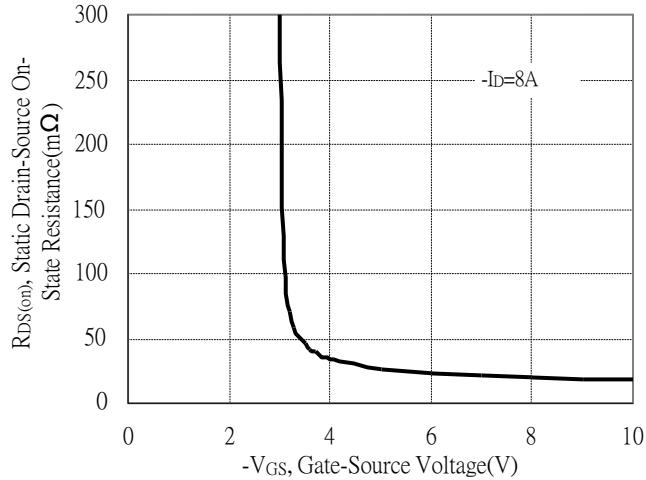
Static Drain-Source On-State resistance vs Drain Current



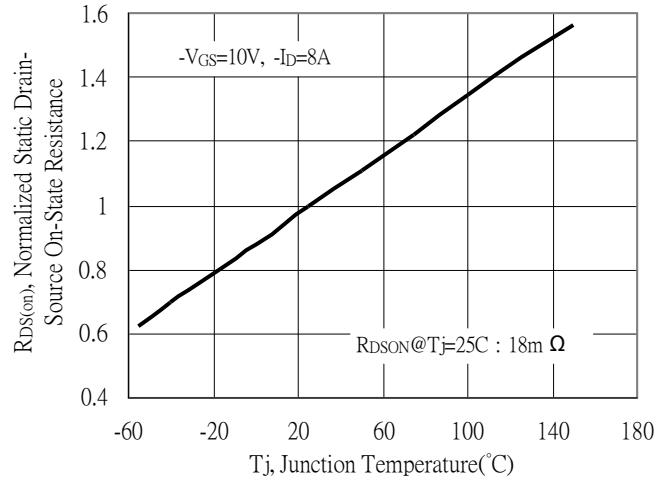
Reverse Drain Current vs Source-Drain Voltage



Static Drain-Source On-State Resistance vs Gate-Source Voltage

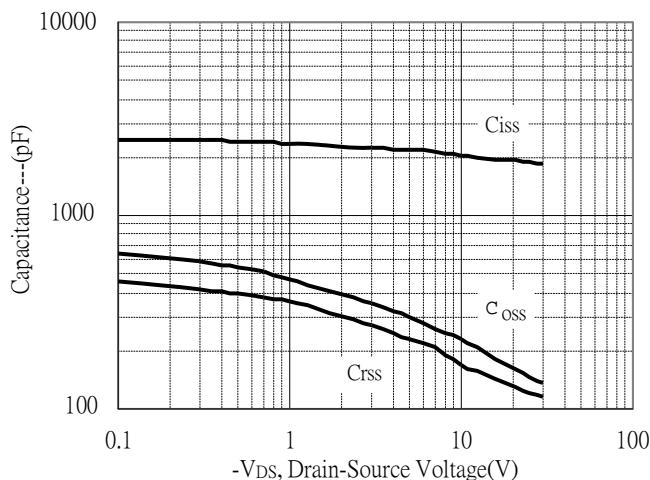


Drain-Source On-State Resistance vs Junction Temperature

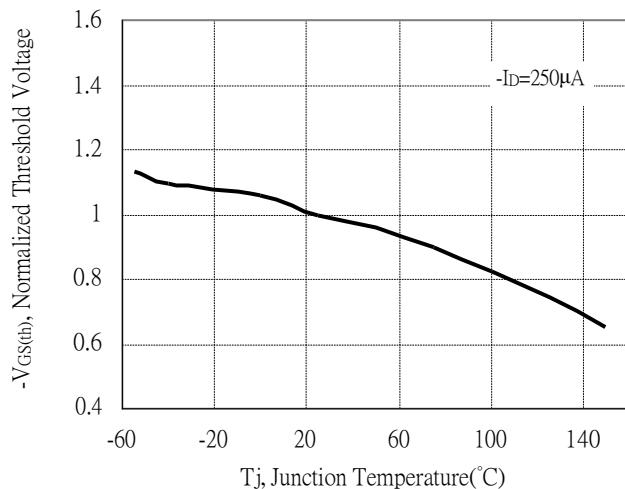


Typical Characteristics(Cont.)

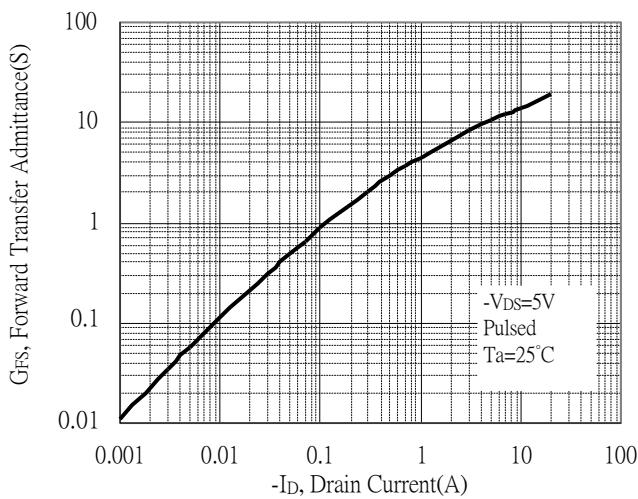
Capacitance vs Drain-to-Source Voltage



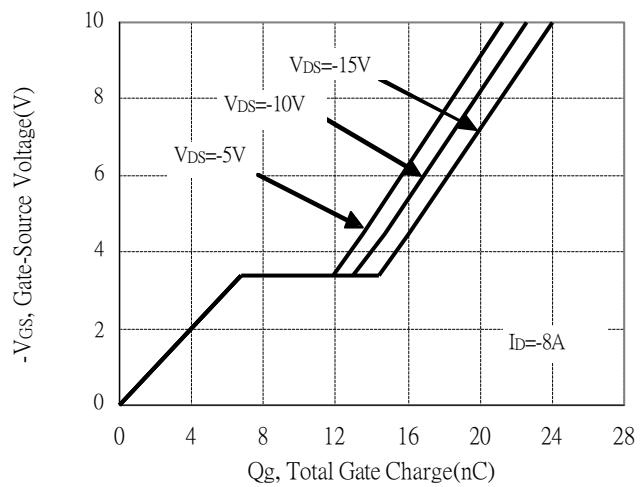
Threshold Voltage vs Junction Temperature



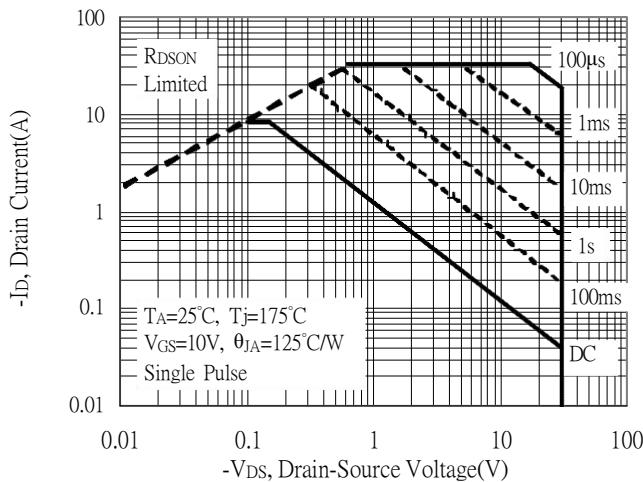
Forward Transfer Admittance vs Drain Current



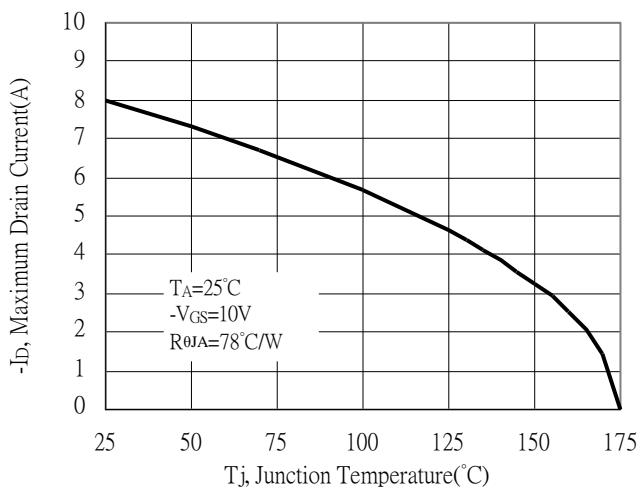
Gate Charge Characteristics



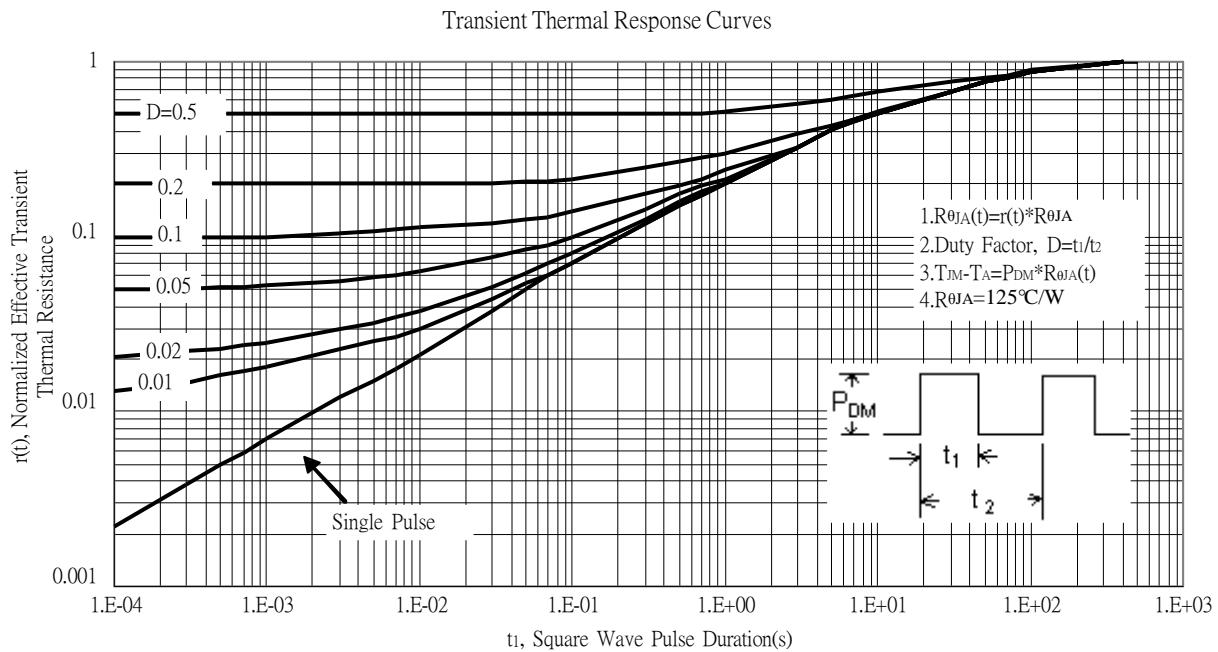
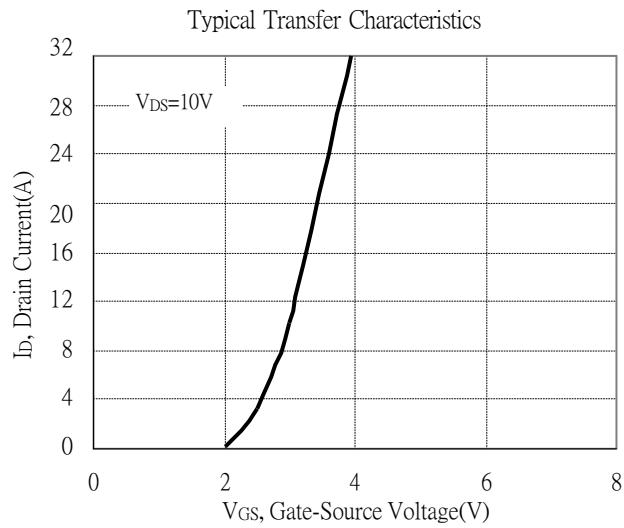
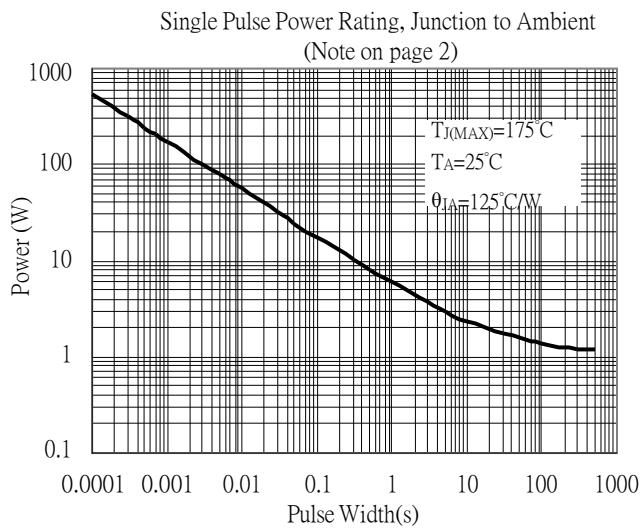
Maximum Safe Operating Area



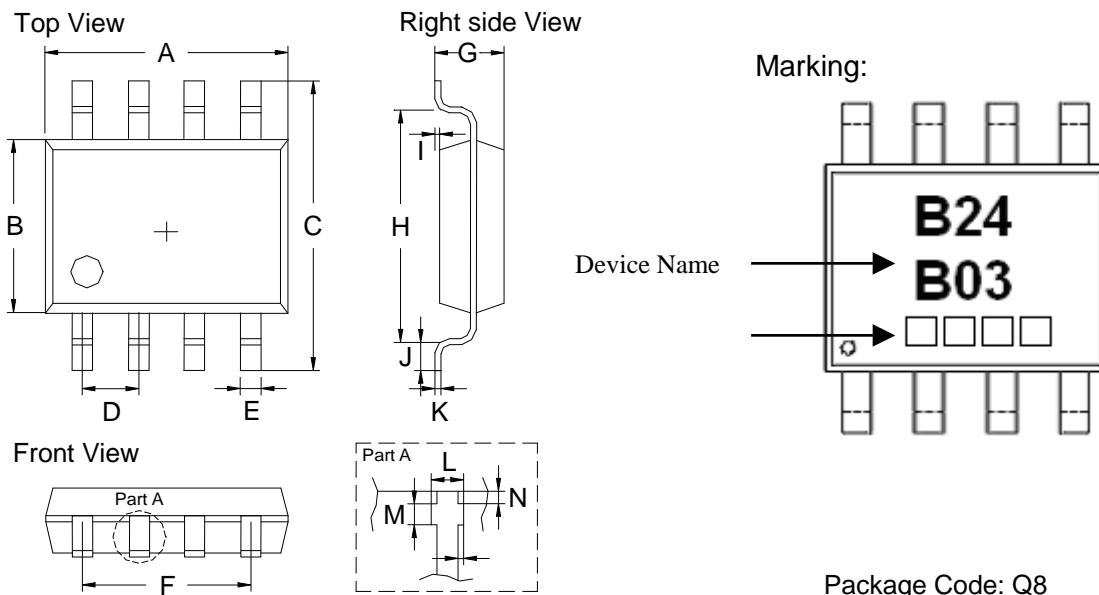
Maximum Drain Current vs Junction Temperature



Typical Characteristics(Cont.)



SOP-8 Dimension



*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1850	0.2007	4.70	5.10	I	0.0031	0.0110	0.08	0.28
B	0.1457	0.1614	3.70	4.10	J	0.0157	0.0323	0.40	0.83
C	0.2283	0.2441	5.80	6.20	K	0.0074	0.0102	0.19	0.26
D	0.0500*		1.27*		L	0.0145	0.0204	0.37	0.52
E	0.0130	0.0201	0.33	0.51	M	0.0118	0.0197	0.30	0.50
F	0.1472	0.1527	3.74	3.88	N	0.0031	0.0051	0.08	0.13
G	0.0472	0.0638	1.20	1.62	O	0.0000	0.0059	0.00	0.15
H	0.1889	0.2007	4.80	5.10					